

REMARKS

Claims 6, 8, 11, and 14 are pending in the application. Independent claims 6 and 11 have been amended to recite a "single-layer substrate." The amendments are fully supported by the application as originally filed (see, e.g., specification at page 4, lines 9-12).

As amended, independent claims 6 and 11 recite a ball grid array (BGA) package including a "single-layer substrate," in which an electrically-conductive bridge is mounted to span in an overhead manner across an interposing electrically-conductive trace so as to electrically connect bond fingers to corresponding vias. Because the BGA package is implemented on a single-layer substrate rather than a multi-layer substrate, the trace layout can be simplified and implemented in a more cost-effective manner than the prior art (see, e.g., specification at page 4, lines 9-12).

Claims 6 and 14 were rejected under 35 USC 103(a) as being unpatentable over "Applicant's Prior Art Figures 3 and 4 (APAF)" in view of Japanese Publication 60-157238 to "Takahama". Claim 8 was rejected under 35 USC 103(a) as being unpatentable over APAF in view of Takahama, and further in view of U.S. Patent 3,560,256 to Abrams. Claim 11 was rejected under 35 USC 103(a) as being unpatentable over APAF in view of Takahama and Abrams. These rejections are respectfully traversed.

The proposed combinations of "APAF" in view of the Takahama and/or Abrams do not teach or suggest a ball grid array package including at least a single-layer substrate.

In PRIOR ART FIG. 4 of the application (or "APAF"), a multi-layer substrate is used. For example, referring to FIG. 4, a multi-layer substrate 10' has an upper layer 11' and a bottom layer 12' (see, e.g., specification at page 3, lines 4-9). The use of a *multi-layer substrate* has drawbacks such as increased complexity and higher materials costs (see page 3, lines 13-15).

In other words, "APAF" discloses the use of a *multi-layer substrate*. The Takahama and Abrams references fail to remedy the deficiencies of "APAF."

In contrast, the Applicant's claimed invention recites a single-layer substrate, which results in a simplified trace layout and lower material costs.

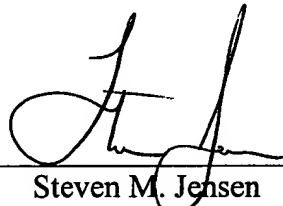
For at least the reasons described above, the proposed combinations of "APAF" in view of the Takahama and/or Abrams references do not teach or suggest the Applicant's claimed invention as recited in independent claims 6 and 11. Therefore, independent claims 6 and 11 and their respective dependent claims 8 and 14 are patentable over the proposed combinations.

It is believed the application is in condition for immediate allowance, which action is earnestly solicited.

Respectfully submitted,

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